

SUM110P06-07L

Vishay Siliconix

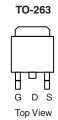
P-Channel 60-V (D-S) 175 °C MOSFET

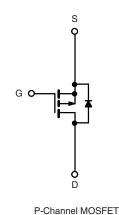
PRODUCT SUMMARY			
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A) ^d	
- 60	0.0069 at V _{GS} = - 10 V	- 110	
	0.0088 at V _{GS} = - 4.5 V	- 110	

FEATURES

- TrenchFET[®] Power MOSFET
- Package with Low Thermal Resistance







Ordering Information: SUM110P06-07L SUM110P06-07L-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS	C = 25 °C, unless other	wise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20	- V	
Continuous Drain Current ^d	T _C = 25 °C		- 110		
(T _J = 175 °C)	T _C = 125 °C		- 95	_	
Pulsed Drain Current		I _{DM}	- 240	- A	
Avalanche Current	L = 0.1 mH	I _{AS}	- 75		
Single Pulse Avalanche Energy ^a	L = 0.1 mm	E _{AS}	281	mJ	
Deven D'estission	T _C = 25 °C	D	375 ^c		
Power Dissipation	$T_{C} = 25 \text{ °C}$ $T_{A} = 25 \text{ °C}^{b}$	P _D	3.75	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Typical	Unit
Junction-to-Ambient	PCB Mount ^b	R _{thJA}	40	°C/W
Junction-to-Case		R _{thJC}	0.4	0/11

Notes:

a. Duty cycle \leq 1 %.

b. When Mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Limited by package.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			- V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μΑ	
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			А	
Drain-Source On-State Resistance ^a		V _{GS} = - 10 V, I _D = - 30 A		0.0055	0.0069		
	r	V_{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.0115	0	
	r _{DS(on)}	V_{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C			0.0138	Ω	
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -20 \text{ A}$		0.007	0.0088		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		11400		pF	
Output Capacitance	C _{oss}			1200			
Reverse Transfer Capacitance	C _{rss}			900			
Total Gate Charge ^c	Qg			230	345	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -110 \text{ A}$		50			
Gate-Drain Charge ^c	Q _{gd}			60			
Gate Resistance	Rg	f = 1.0 MHz		3		Ω	
Turn-On Delay Time ^c	t _{d(on)}			20	30	ns	
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 0.27 Ω		160	240		
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D}\cong$ - 110 A, V_{GEN} = - 10 V, R_{g} = 2.5 Ω		200	300		
Fall Time ^c	t _f			240	360		
Source-Drain Diode Ratings and Cha	aracteristics	T _C = 25 °C ^b					
Continuous Current	۱ _S				- 110	•	
Pulsed Current	I _{SM}				- 240	A	
Forward Voltage ^a	V _{SD}	I _F = - 85 A, V _{GS} = 0 V		- 1.0	-1.5	V	
Reverse Recovery Time	t _{rr}			65	100	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = - 85 A, di/dt = 100 A/μs		- 4.2	- 6.3	Α	
Reverse Recovery Charge	Q _{rr}	1		0.14	0.32	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

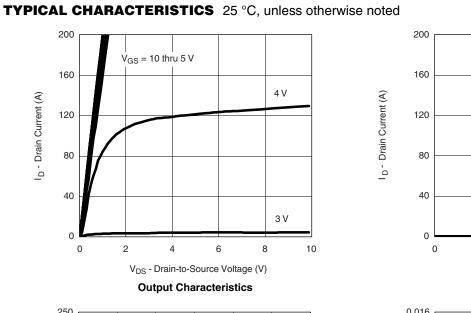
b. Guaranteed by design, not subject to production testing.

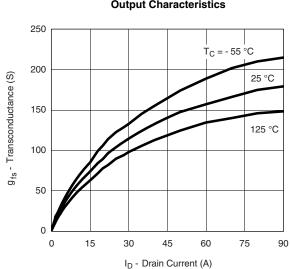
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

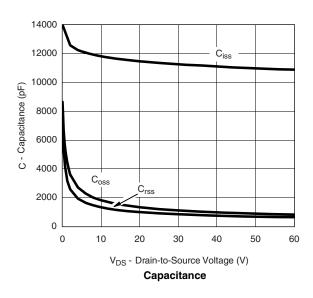
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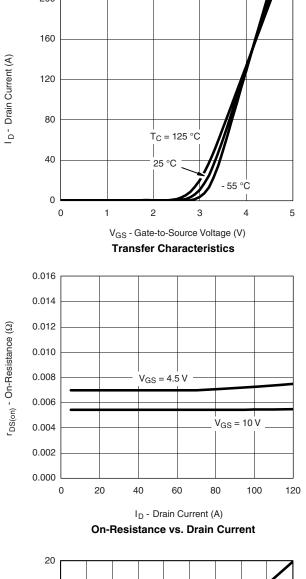
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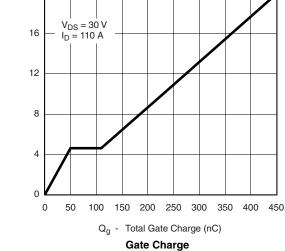




Transconductance







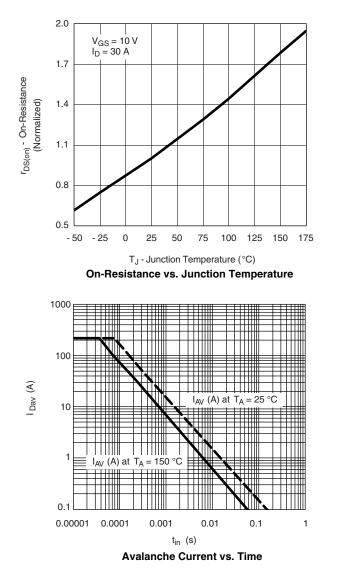
V GS - Gate-to-Source Voltage (V)

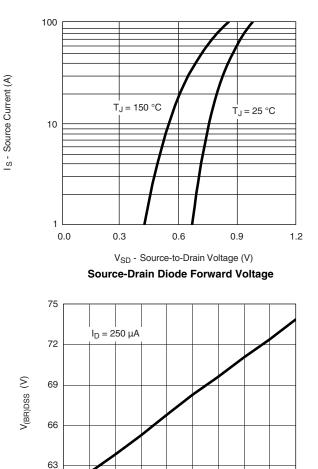
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





60

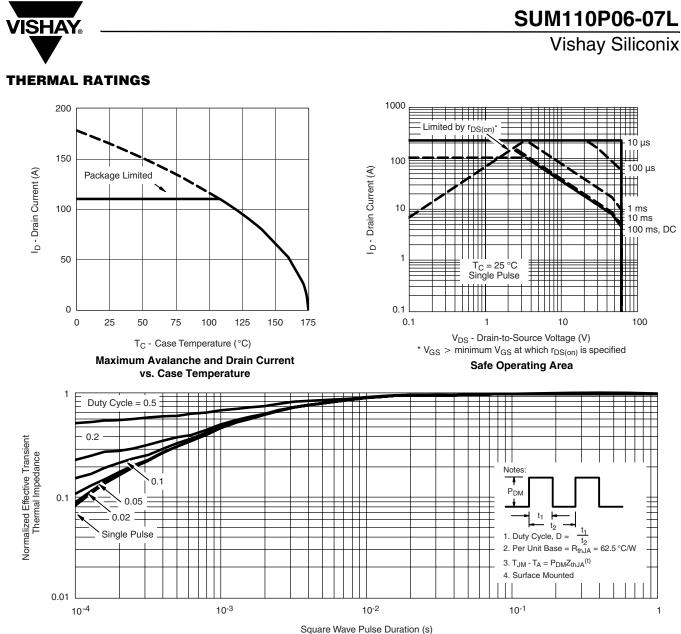
- 50 - 25

0 25 50 75 100 125

T_J - Junction Temperature (°C) Drain Source Breakdown vs.

Junction Temperature

150 175



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72439.

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